



## Material Content Data Sheet



<b>Sales Product Name</b>		BSD314SPE H6327		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000974768						
<b>Package</b>		PG-SOT363-6-6		<b>Weight*</b>		6.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.003	0.05		472	
	noble metal	gold	7440-57-5	0.012	0.18		1831	
	inorganic material	silicon	7440-21-3	0.187	2.79	3.02	27936	30239
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		493	
	non noble metal	chromium	7440-47-3	0.010	0.15		1478	
	non noble metal	copper	7440-50-8	3.275	49.06	49.27	490508	492578
wire	non noble metal	copper	7440-50-8	0.051	0.76	0.76	7639	7639
encapsulation	organic material	carbon black	1333-86-4	0.028	0.43		4262	
	plastics	epoxy resin	-	0.612	9.16		91625	
	inorganic material	silicondioxide	60676-86-0	2.205	33.03	42.62	330277	426164
leadfinish	non noble metal	tin	7440-31-5	0.213	3.19	3.19	31931	31931
plating	noble metal	silver	7440-22-4	0.076	1.14	1.14	11449	11449
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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